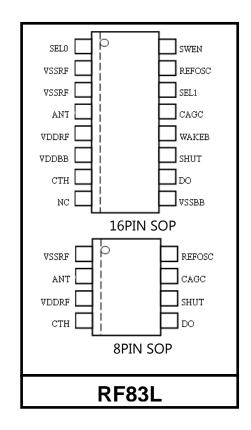
RF83L 300MHz-440MHz ASK/OOK Receiver

Features

- 300MHz to 440MHz frequency range
- Operational voltage: 2.2V-3.6V
- High receiver sensitivity: -108dBm
- Data-rate up to 10kbps (fixed-mode)
- Low Power Consumption
 - 2.5mA fully operational at 315MHZ,
 3.5mA fully operational at 433MHZ,
 - $0.9\mu A$ in shutdown
 - 300µA in polled operation (10:1 duty-cycle)
- Wake-up output flag to enable decoders and microprocessors
- Very low RF re-radiation at the antenna
- Highly integrated with extremely low external part count

Applications

- Automotive Remote Keyless Entry (RKE)
- Remote controls
- Remote fan and light control
- Garage door and gate openers



The RF83L is a single chip ASK/OOK (ON-OFF Keyed) RF receiver IC. This device is a true "antenna-in to data-out" monolithic device. All RF and IF tuning are accomplished automatically within the IC which eliminates manual tuning and reduces production costs. The result is a highly reliable yet low cost solution. The RF83L is a fully featured part in 16-pin packaging and The RF83A/B/C/DL is a same part packaged in 8-pin packaging with a reduced feature set.

The RF83L provides two additional functions, (1) a Shutdown pin, which may be used to turn the device off for duty-cycled operation, and (2) a "Wake-up" output, which provides an output flag indicating when an RF signal is present. These features make the RF83L ideal for low and ultra-low power applications, such as RKE and remote controls

All IF filtering and post-detection (demodulator) data filtering is provided within the RF83L, so no external filters are necessary. One of four demodulator filter bandwidths may be selected externally by the user.

The RF83L offer two modes of operation; fixed-mode (FIX) and sweep-mode (SWP). In fixed mode the RF83L functions as a conventional super-heterodyne receiver. In sweep mode the RF83L sweeps a wider RF spectrum. Fixed-mode provides better selectivity and sensitivity performance and sweep mode enables the RF83L to be used with low cost, imprecise transmitters.

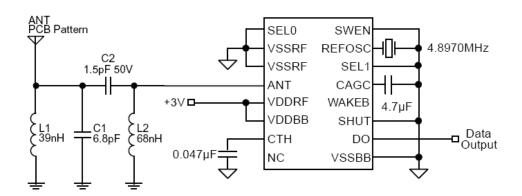


1. Contents

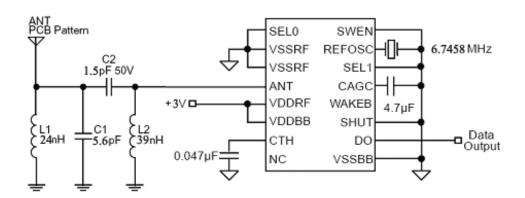
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2. Typical Application



315MHz 800bps On-Off Keyed Receiver



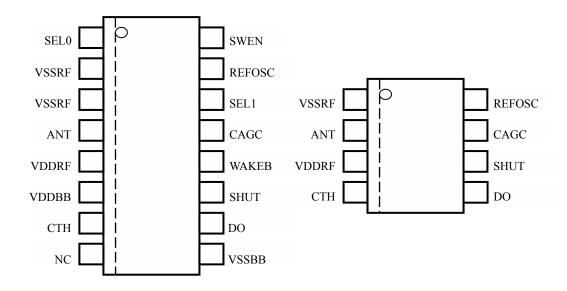
433.92MHz 800bps On-Off Keyed Receiver



3. Ordering Information

| Part Number | Demodulator | Operating | Shut Down | WAKEB | Package |
|-------------|--------------|-----------|-----------|-------------|------------|
| | Bandwidth | Mode | | Output Flag | |
| RF83L | User | Fixed or | Yes | Yes | 16-Pin SOP |
| | Programmable | Sweep | | | |
| RF83AL | 5000Hz | Sweep | No | Yes | 8-Pin SOP |
| RF83BL | 1250Hz | Fixed | Yes | No | 8-Pin SOP |
| RF83CL | 2500Hz | Fixed | Yes | No | 8-Pin SOP |
| RF83DL | 5000Hz | Fixed | Yes | No | 8-Pin SOP |

4. Pin Configuration



Standard 16-Pin or 8-Pin SOP (M) Packages



5. 8-Pin Options

The standard 16-pin package allows complete control of all configurable features. Some reduced function 8-pin versions are also available.

For high-volume applications additional customized 8-pin devices can be produced. SWEN, SEL0 and SEL1 pins are internally bonded to reduce the pin count. Pin 6 may be configured as either SHUT or WAKEB.

| CELO | SEL1 | Demodulator Bandwidth | | | |
|------|------|-----------------------|------------|--|--|
| SEL0 | | Sweep Mode | Fixed Mode | | |
| 1 | 1 | 5000 Hz | 10000Hz | | |
| 0 | 1 | 2500 Hz | 5000Hz | | |
| 1 | 0 | 1250 Hz | 2500 Hz | | |
| 0 | 0 | 625 Hz | 1250 Hz | | |

Table 1. Nominal Demodulator Filter Bandwidth vs. SEL0, SEL1 and Operating Mode

6. Pin Description

| Pin Number | Pin Number | Pin | Pin Function |
|-------------|--------------------------------|--------|--|
| 16-Pin Pkg. | 8-Pin Pkg. | Name | |
| 1 | | SEL0 | Bandwidth Selection Bit 0 (Digital Input): Used in |
| | | | conjunction with SEL1 to set the desired demodulator filter |
| | | | bandwidth. See Table 1. Internally pulled-up to VDDRF |
| 2, 3 | 1 | VSSRF | RF Power Supply: Ground return to the RF section power |
| 2, 3 | 1 | VOSICI | supply. |
| 4 | 2 | ANT | Antenna (Analog Input): For optimal performance the |
| | | | ANT pin should be impedance matched to the antenna. See |
| | | | "Applications Information" for information on input |
| | | | impedance and matching techniques |
| 5 | 5 VDDRF RF Power Supply: Posit | | RF Power Supply: Positive supply input for the RF section |
| 3 | 3 | V DDKI | of the IC |
| 6 | | VDDBB | Base-Band Power Supply: Positive supply input for the |
| | | | baseband section (digital section) of the IC |
| 7 | 4 | CTH | Data Slicing Threshold Capacitor (Analog I/O): Capacitor |
| | | | connected to this pin extracts the dc average value from the |
| | | | demodulated waveform which becomes the reference for |
| | | | the internal data slicing comparator |
| 8 | | NC | Not internally connected |
| 9 | | VSSBB | Base-Band Power Supply: Ground return to the baseband |
| | | | section power supply |



| 10 | 5 | DO | Data Output (Digital Output) | | |
|----|---|--------|---|--|--|
| 11 | 6 | SHUT | Shutdown (Digital Input): Shutdown-mode logic-level | | |
| | | | control input. Pull low to enable the receiver. Internally | | |
| | | | pulled-up to VDDRF | | |
| 12 | | WAKEB | Wakeup (Digital Output): Active-low output that indicates | | |
| | | | detection of an incoming RF signal | | |
| 13 | 7 | CAGC | Automatic Gain Control (Analog I/O): Connect an external | | |
| | | | capacitor to set the attack/decay rate of the on-chip | | |
| | | | automatic gain control | | |
| 14 | | SEL1 | Bandwidth Selection Bit 1 (Digital Input): Used in | | |
| | | | conjunction with SEL0 to set the desired demodulator filter | | |
| | | | bandwidth. See Table 1. Internally pulled-up to VDDRF | | |
| 15 | 8 | REFOSC | Reference Oscillator: Timing reference, sets the RF receive | | |
| 13 | 8 | REFUSC | frequency. | | |
| 16 | | SWEN | Sweep-Mode Enable (Digital Input): Sweep- or | | |
| | | | Fixed-mode operation control input. SWEN high = sweep | | |
| | | | mode; SWEN low = conventional superheterodyne | | |
| | | | receiver. Internally pulled-up to VDDRF | | |

7. Absolute Maximum Ratings (Note 1)

| Supply Voltage (V _{DDRF} , V _{DDBB}) | +5.5V |
|---|--------------------------------|
| Input/Output Voltage (V _{I/O}) | V_{SS} -0.3 to V_{DD} +0.3 |
| Junction Temperature (T _J) | +150°C |
| Storage Temperature Range (T _S) | −65°C to +150°C |
| Lead Temperature (soldering, 10 sec.) | +260°C |
| ESD Rating | Note 3 |

8.Operating Ratings (Note 2)

| RF Frequency Range | 300MHz to 440MHz |
|---|----------------------------|
| Supply Voltage (VDDRF, VDDBB, 300~440MHz) | +2.2V to +3.6V |
| Data Duty-Cycle | 20% to 80% |
| Reference Oscillator Input Range | $0.1V_{PP}$ to $1.5V_{PP}$ |
| Ambient Temperature (T _A) | −35°C to +85°C |



9. Electrical Characteristics

$$\begin{split} &V_{DDRF}=V_{DDBB}=V_{DD} \text{ where } +3 \leq V_{DD} \leq 3.3 \text{V}, \ V_{SS}=0 \text{V}; \ C_{AGC}=4.7 \mu \text{F}, \ C_{TH}=100 \text{nF}; \ \text{SEL0} \\ &= \text{SEL1}=V_{SS}; \ \text{fixed mode (SWEN}=V_{SS}); \ f_{REFOSC}=4.8970 \text{MHz (equivalent to } f_{RF}=315 \text{MHz)}; \\ &\text{data-rate}=1 \text{kbps (Manchester encoded)}. \ T_A=25 ^{\circ}\text{C}, \ \textbf{bold} \ \text{values indicate } -40 ^{\circ}\text{C} \leq T_A \leq +85 ^{\circ}\text{C}; \\ &\text{current flow into device pins is positive; unless noted.} \end{split}$$

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|------------|-------------------|---|-----|-----|-----|-------|
| I_{OP} | Operating Current | continuous operation, $f_{RF} = 315MHz$ | | 2.5 | 3.5 | mA |
| | | polled with 10:1 duty cycle, $f_{RF} = 315MHz$ | | 300 | | μА |
| | | continuous operation, $f_{RF} = 433.92MHz$ | | 3 | 4 | mA |
| | | polled with 10:1 duty cycle, $f_{RF} = 433.92MHz$ | | 500 | | μА |
| I_{STBY} | Standby Current | $V_{SHUT} = V_{DD}$ | | 0.9 | | μА |

RF Section, IF Section

| | Receiver Sensitivity (Note 4) | $f_{RF} = 315MHz$ | -108 | dBm |
|-------------------|-------------------------------|--|------|-------|
| | | $f_{RF} = 433.92MHz$ | -108 | dBm |
| $f_{ m IF}$ | IF Center Frequency | Note 6 | 0.86 | MHz |
| f_{BW} | IF Bandwidth | Note 6 | 0.43 | MHz |
| | Maximum Receiver Input | $R_{SC} = 50\Omega$ | -20 | dBm |
| | Spurious Reverse Isolation | ANT pin, $R_{SC} = 50\Omega$, Note 5 | 30 | μVrms |
| | AGC Attack to Decay Ratio | $t_{ATTACK} \div t_{DECAY}$ | 0.1 | |
| | AGC Leakage Current | $T_A = +85$ °C | ±100 | nA |

Reference Oscillator

| Z _{REFOSC} | Reference Oscillator Input Impedance | Note 8 | 290 | kΩ |
|---------------------|--------------------------------------|--------|-----|----|
| | Reference Oscillator Source Current | | 5.2 | uA |

Demodulator

| Z_{CTH} | CTH Source Impedance | Note 7 | 145 | kΩ |
|-------------------------|-----------------------------------|--|------|----|
| I _{ZCTH(leak)} | CTH Leakage Current | $T_A = +85^{\circ}C$ | ±100 | nA |
| | Demodulator Filter Bandwidth | $V_{SEL0} = V_{DD}$. $V_{SEL1} = V_{DD}$ | 4000 | Hz |
| | Sweep Mode | $V_{\text{SEL0}} = V_{\text{SS}}. \ V_{\text{SEL1}} = V_{\text{DD}}$ | 2000 | Hz |
| | $(SWEN = V_{DD} \text{ or OPEN})$ | $V_{SEL0} = V_{DD.} V_{SEL1} = V_{SS}$ | 1000 | Hz |
| | Note 6 | $V_{SEL0} = V_{SS}. \ V_{SEL1} = V_{SS}$ | 500 | Hz |



| (SWEN = VSS) Note 6 $V_{SEL0} = V_{SS}. V_{SEL1} = V_{SS}$ 1000 H | V SELO = V SS · V SELI = V SS 1000 IIZ | Fi | ixed Mode | $\begin{aligned} &V_{SEL0} = V_{DD}. \ V_{SEL1} = V_{DD} \\ &V_{SEL0} = V_{SS}. \ V_{SEL1} = V_{DD} \\ &V_{SEL0} = V_{DD}. \ V_{SEL1} = V_{SS} \\ &V_{SEL0} = V_{SS}. \ V_{SEL1} = V_{SS} \end{aligned}$ | | 8000 4000 2000 1000 | | Hz Hz Hz Hz |
|--|--|----|-----------|--|--|------------------------------|--|----------------------|
|--|--|----|-----------|--|--|------------------------------|--|----------------------|

Digital/Control Section

| V _{IN(high)} | Input-High Voltage | SEL0, SEL1, SWEN | | | 0.8 | V_{DD} |
|------------------------|----------------------------|--|-----|----|-----|-------------------|
| V _{IN(low)} | Input-Low Voltage | SEL0, SEL1, SWEN | 0.2 | | | V_{DD} |
| I_{OUT} | Output Current | DO, WAKEB pins, push-pull | | 10 | | μΑ |
| $V_{\text{OUT(high)}}$ | Output High Voltage | DO, WAKEB pins, $I_{OUT} = -1 \mu A$ | 0.9 | | | V_{DD} |
| V _{OUT(low)} | Output Low Voltage | DO, WAKEB pins, $I_{OUT} = +1\mu A$ | | | 0.1 | V_{DD} |
| t_R, t_F | Output Rise and Fall Times | DO, WAKEB pins, C _{LOAD} = 15pF | | 10 | | μs |

- **Note 1:** Exceeding the absolute maximum rating may damage the device.
- **Note 2:** The device is not guaranteed to function outside its operating rating.
- **Note 3:** Devices are ESD sensitive, use appropriate ESD precautions. Meets class 1 ESD test requirements, (human body model HBM), in accordance with MIL-STD-883C, method 3015. Do not operate or store near strong electrostatic fields.
- **Note 4:** Sensitivity is defined as the average signal level measured at the input necessary to achieve 10^{-2} BER (bit error rate). The RF input is assumed to be matched to 50Ω .
- **Note 5:** Spurious reverse isolation represents the spurious components which appear on the RF input pin (ANT) measured into 50Ω with an input RF matching network.
- **Note 6:** Parameter scales linearly with reference oscillator frequency f_T . For any reference oscillator frequency other than 4.8970MHz, compute new parameter value as the ratio:

$$\frac{f_{REFOSC}MHz}{4.8970MHz}$$
 × (parameter value at 4.8970MHz)

Note 7: Parameter scales inversely with reference oscillator frequency f_T . For any reference oscillator frequency other than 4.8970MHz, compute new parameter value as the ratio:

$$\frac{4.8970 MHz}{f_{REFOSC}MHz}$$
 × (parameter value at 4.8970MHz)

Note 8: Series resistance of the resonator (ceramic resonator or crystal) should be minimized to the extent possible. In cases where the resonator series resistance is too great, the oscillator may oscillate at a diminished peak-to-peak level, or may fail to oscillate entirely. HopeRF recommends that series resistances for ceramic resonators and crystals not exceed 50Ohms and 100Ohms respectively. Refer to Application Hint 35 for crystal recommendations.



10. Functional Diagram

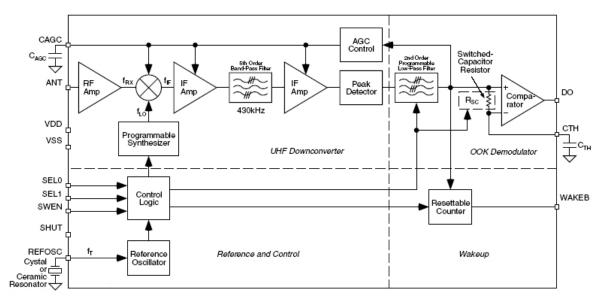


Figure 1. RF83L Block Diagram

11. Applications Information and Functional Description

Refer to figure 1 "RF83L Block Diagram". Identified in the block diagram are the four sections of the IC: UHF Downconverter, OOK Demodulator, Reference and Control, and Wakeup. Also shown in the figure are two capacitors (CTH, CAGC) and one timing component, usually a crystal or ceramic resonator. With the exception of a supply decoupling capacitor, and antenna impedance matching network, these are the only external components needed by the RF83L to assemble a complete UHF receiver.

For optimal performance is highly recommended that the RF83L is impedance matched to the antenna, the matching network will add an additional two or three components.

Four control inputs are shown in the block diagram: SEL0, SEL1, SWEN, and SHUT. Using these logic inputs, the user can control the operating mode and selectable features of the IC. These inputs are CMOS compatible, and are internally pulled-up. IF Bandpass Filter Roll-off response of the IF Filter is 5th order, while the demodulator data filter exhibits a 2nd order response.

12. Design Steps

The following steps are the basic design steps for using the RF83L receiver:

- 1) Select the operating mode (sweep or fixed)
- 2) Select the reference oscillator
- 3) Select the CTH capacitor
- 4) Select the CAGC capacitor
- 5) Select the demodulator filter bandwidth



12.1. Step 1: Selecting the Operating Mode

12.1.1. Fixed-Mode Operation

For applications where the transmit frequency is accurately set (that is, applications where a SAW or crystal-based transmitter is used) the RF83L may be configured as a standard superheterodyne receiver (fixed mode). In fixed-mode operation the RF bandwidth is narrower making the receiver less susceptible to interfering signals. Fixed mode is selected by connecting SWEN to ground.

12.1.2. Sweep-Mode Operation

When used in conjunction with low-cost L-C transmitters the RF83L should be configured in sweep-mode. In sweep-mode, while the topology is still superheterodyne, the LO (local oscillator) is swept over a range of frequencies at rates greater than the data rate. This technique effectively increases the RF bandwidth of the RF83L, allowing the device to operate in applications where significant transmitter-receiver frequency misalignment may exist. The transmit frequency may vary up to $\pm 0.5\%$ over initial tolerance, aging, and temperature. In sweep-mode a band approximately 1.5% around the nominal transmit frequency is captured. The transmitter may drift up to $\pm 0.5\%$ without the need to retune the receiver and without impacting system performance.

The swept-LO technique does not affect the IF bandwidth, therefore noise performance is not degraded relative to fixed mode. The IF bandwidth is 430kHz whether the device is operating in fixed or sweep-mode.

Due to limitations imposed by the LO sweeping process, the upper limit on data rate in sweep mode is approximately 5.0kbps.

Similar performance is not currently available with crystal-based superheterodyne receivers which can operate only with SAW- or crystal-based transmitters.

In sweep-mode, a range reduction will occur in installations where there is a strong interferer in the swept RF band. This is because the process indiscriminately includes all signals within the sweep range. An RF83L may be used in place of a superregenerative receiver in most applications.

12.2. Step 2: Selecting the Reference Oscillator

All timing and tuning operations on the RF83L are derived from the internal Colpitts reference oscillator. Timing and tuning is controlled through the REFOSC pin in one of three ways:

- 1) Connect a ceramic resonator
- 2) Connect a crystal
- 3) Drive this pin with an external timing signal

The specific reference frequency required is related to the system transmit frequency and to the operating mode of the receiver as set by the SWEN pin.



12.2.1. Crystal or Ceramic Resonator Selection

If operating in fixed-mode, a crystal is recommended. In sweep-mode either a crystal or ceramic resonator may be used. When a crystal of ceramic resonator is used the minimum voltage is 300mV_{PP} . If using an externally applied signal it should be AC-coupled and limited to the operating range of 0.1V_{PP} to 1.5V_{PP} .

12.2.2. Selecting Reference Oscillator Frequency f_T (Fixed Mode)

As with any superheterodyne receiver, the mixing between the internal LO (local oscillator) frequency f_{LO} and the incoming transmit frequency f_{TX} ideally must equal the IF center frequency. Equation 1 may be used to compute the appropriate f_{LO} for a given f_{TX} :

(1)
$$f_{LO} = f_{TX} \pm (0.86 \frac{f_{TX}}{315})$$

Frequencies f_{TX} and f_{LO} are in MHz. Note that two values of f_{LO} exist for any given f_{TX} , distinguished as "high-side mixing" and "low-side mixing." High-side mixing results in an image frequency above the frequency of interest and low-side mixing results in a frequency below.

After choosing one of the two acceptable values of f_{LO} , use Equation 2 to compute the reference oscillator frequency f_T :

(2)
$$f_T = \frac{F_{LO}}{64.5}$$

Frequency f_T is in MHz. Connect a crystal of frequency f_T to REFOSC on the RF83L. Four-decimal-place accuracy on the frequency is generally adequate. The following table identifies f_T for some common transmit frequencies when the RF83L is operated in fixed mode.

| Transmit Frequency (f _{TX}) | Reference Oscillator Frequency (f _T) |
|---------------------------------------|--|
| 315MHz | 4.8970 MHz |
| 390 MHz | 6.0630 MHz |
| 418 MHz | 6.4983 MHz |
| 433.92 MHz | 6.7458 MHz |

Table 2. Fixed Mode Recommended Reference Oscillator Values For Typical Transmit Frequencies (high-side mixing)

12.2.3. Selecting REFOSC Frequency f_T (Sweep Mode)

Selection of the reference oscillator frequency fT in sweep mode is much simpler than in fixed mode due to the LO sweeping process. Also, accuracy requirements of the frequency reference component are significantly relaxed.

In sweep mode, f_T is given by Equation 3:

(3)
$$f_T = \frac{F_{LO}}{64.25}$$



In SWEEP mode a reference oscillator with frequency accurate to two-decimal-places is generally adequate. A crystal may be used and may be necessary in some cases if the transmit frequency is particularly imprecise.

| Transmit Frequency (f _{TX}) | Reference Oscillator Frequency (f_T) |
|---------------------------------------|--|
| 315MHz | 4.88 MHz |
| 390 MHz | 6.05 MHz |
| 418 MHz | 6.48 MHz |
| 433.92 MHz | 6.73 MHz |

Table 3. Recommended Reference Oscillator Values For Typical Transmit Frequencies (sweep-mode)

12.3. Step 3: Selecting the C_{TH} Capacitor

Extraction of the dc value of the demodulated signal for purposes of logic-level data slicing is accomplished using the external threshold capacitor CTH and the on-chip switched-capacitor "resistor" RSC, shown in the block diagram.

Slicing level time constant values vary somewhat with decoder type, data pattern, and data rate, but typically values range from 5ms to 50ms. Optimization of the value of CTH is required to maximize range.

12.3.1. Selecting Capacitor C_{TH}

The first step in the process is selection of a data-slicing-level time constant. This selection is strongly dependent on system issues including system decode response time and data code structure (that is, existence of data preamble, etc.). This issue is covered in more detail in Application Note 22.

The effective resistance of R_{SC} is listed in the electrical characteristics table as $145k\Omega$ at 315MHz, this value scales linearly with frequency. Source impedance of the CTH pin at other frequencies is given by equation (4), where f_T is in MHz:

(4)
$$R_{SC} = 145 \text{k}\Omega$$
 $\frac{4.8970}{f_T}$

 τ of 5x the bit-rate is recommended. Assuming that a slicing level time constant τ has been established, capacitor CTH may be computed using equation

$$(5) C_{TH} = \frac{\tau}{R_{SC}}$$

A standard $\pm 20\%$ X7R ceramic capacitor is generally sufficient. Refer to Application Hint 42 for C_{TH} and C_{AGC} selection examples.



12.4. Step 4: Selecting the C_{AGC} Capacitor

The signal path has AGC (automatic gain control) to increase input dynamic range. The attack time constant of the AGC is set externally by the value of the C_{AGC} capacitor connected to the CAGC pin of the device. To maximize system range, it is important to keep the AGC control voltage ripple low, preferably under 10mVpp once the control voltage has attained its quiescent value. For this reason capacitor values of at least $0.47\mu F$ are recommended.

The AGC control voltage is carefully managed on-chip to allow duty-cycle operation of the RF83L. When the device is placed into shutdown mode (SHUT pin pulled high), the AGC capacitor floats to retain the voltage. When operation is resumed, only the voltage droop due to capacitor leakage must be replenished. A relatively low-leakage capacitor is recommended when the devices are used in duty-cycled operation.

To further enhance duty-cycled operation, the AGC push and pull currents are boosted for approximately 10ms immediately after the device is taken out of shutdown. This compensates for AGC capacitor voltage droop and reduces the time to restore the correct AGC voltage. The current is boosted by a factor of 45.

12.4.1. Selecting C_{AGC} Capacitor in Continuous Mode

A C_{AGC} capacitor in the range of $0.47\mu F$ to $4.7\mu F$ is typically recommended. The value of the C_{AGC} should be selected to minimize the ripple on the AGC control voltage by using a sufficiently large capacitor. However if the capacitor is too large the AGC may react too slowly to incoming signals. AGC settling time from a completely discharged (zero-volt) state is given approximately by Equation 6:

(6)
$$\Delta t = 1.333 C_{AGC} - 0.44$$

Where: C_{AGC} is in μF , and Δt is in seconds.

12.4.2. Selecting C_{AGC} Capacitor in Duty-Cycle Mode

Voltage droop across the C_{AGC} capacitor during shutdown should be replenished as quickly as possible after the IC is enabled. As mentioned above, the RF83L boosts the push-pull current by a factor of 45 immediately after start-up. This fixed time period is based on the reference oscillator frequency f_T . The time is 10.9ms for $f_T = 6.00 \text{MHz}$, and varies inversely with f_T . The value of C_{AGC} capacitor and the duration of the shutdown time period should be selected such that the droop can be replenished within this 10ms period.

Polarity of the droop is unknown, meaning the AGC voltage could droop up or down. Worst-case from a recovery standpoint is downward droop, since the AGC pull-up current is 1/10th magnitude of the pulldown current. The downward droop is replenished according to the Equation 7:

$$(7) \qquad \frac{I}{C_{AGC}} = \frac{\Delta V}{\Delta t}$$

Where:

I = AGC pullup current for the initial 10ms (67.5 μ A)



 $C_{AGC} = AGC$ capacitor value

 Δt = droop recovery time

 $\Delta V = droop voltage$

For example, if user desires $\Delta t = 10 ms$ and chooses a $4.7 \mu F$ C_{AGC} , then the allowable droop is about 144mV. Using the same equation with 200nA worst case pin leakage and assuming $1 \mu A$ of capacitor leakage in the same direction, the maximum allowable Δt (shutdown time) is about 0.56s for droop recovery in 10ms.

The ratio of decay-to-attack time-constant is fixed at 10:1 (that is, the attack time constant is 1/10th of the decay time constant). Generally the design value of 10:1 is adequate for the vast majority of applications. If adjustment is required the constant may be varied by adding a resistor in parallel with the C_{AGC} capacitor. The value of the resistor must be determined on a case by case basis.

12.5. Step 5: Selecting the Demod Filter Bandwidth

The inputs SEL0 and SEL1 control the demodulator filter bandwidth in four binary steps (625Hz to 5000Hz in sweep, 1250Hz to 10000Hz in fixed mode), see Table 1. Bandwidth must be selected according to the application. The demodulator bandwidth should be set according to equation 8.

(8) Demodulator bandwidth = 0.65 / Shortest pulse-width

It should be noted that the values indicated in table 1 are nominal values. The filter bandwidth scales linearly with frequency so the exact value will depend on the operating frequency. Refer to the "Electrical Characteristics" for the exact filter bandwidth at a chosen frequency.

| GTT A | | Demodulato | Demodulator Bandwidth | | |
|-------|------|------------|-----------------------|--|--|
| SEL0 | SEL1 | Sweep Mode | Fixed Mode | | |
| 1 | 1 | 5000Hz | 10000 Hz | | |
| 0 | 1 | 2500 Hz | 5000 Hz | | |
| 1 | 0 | 1250 Hz | 2500 Hz | | |
| 0 | 0 | 625 Hz | 1250 Hz | | |

Table 1. Nominal Demodulator Filter Bandwidth vs. SEL0, SEL1 and Operating Mode



13. Additional Applications Information

In addition to the basic operation of the RF83L the following enhancements can be made. <u>In particular it is strongly recommended that the antenna impedance is matched to the input of the IC</u>.

13.1. Antenna Impedance Matching

As shown in table 4 the antenna pin input impedance is frequency dependant.

The ANT pin can be matched to 50 Ohms with an L-type circuit. That is, a shunt inductor from the RF input to ground and another in series from the RF input to the antenna pin.

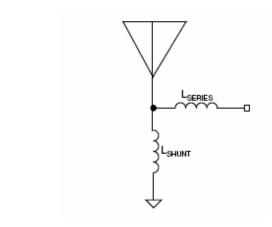
Inductor values may be different from table depending on PCB material, PCB thickness, ground configuration, and how long the traces are in the layout. Values shown were characterized for a 0.031 thickness, FR4 board, solid ground plane on bottom layer, and very short traces. MuRata and Coilcraft wire wound 0603 or 0805 surface mount inductors were tested, however any wire wound inductor with high SRF (self resonance frequency) should do the job.

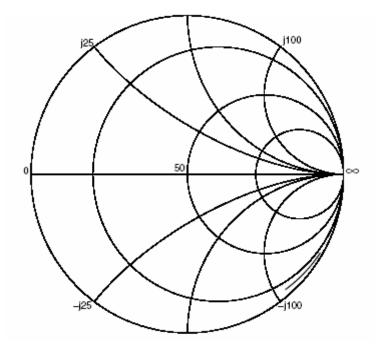
| Frequency | Z _{IN} () | C | I (nII) | I (pII) |
|-----------|--------------------|--------------|-----------------|------------------|
| (MHz) | Z_{11} | S_{11} | $L_{SHUNT}(nH)$ | $L_{SERIES}(nH)$ |
| 300 | 12-j166 | 0.803-j0.529 | 15 | 72 |
| 305 | 12-j165 | 0.800-j0.530 | 15 | 72 |
| 310 | 12-j163 | 0.796-j0.536 | 15 | 72 |
| 315 | 13-j162 | 0.791-j0.536 | 15 | 72 |
| 320 | 12-j160 | 0.789-j0.543 | 15 | 68 |
| 325 | 12-j157 | 0.782-j0.550 | 12 | 68 |
| 330 | 12-j155 | 0.778-j0.556 | 12 | 68 |
| 335 | 12-j152 | 0.770-j0.564 | 12 | 68 |
| 340 | 11—j150 | 0.767-j0.572 | 15 | 56 |
| 345 | 11-j148 | 0.762-j0.578 | 15 | 56 |
| 350 | 11-j145 | 0.753-j0.586 | 12 | 56 |
| 355 | 11-j143 | 0.748-j0.592 | 12 | 56 |
| 360 | 11-j141 | 0.742-j0.597 | 10 | 56 |
| 365 | 11-j139 | 0.735-j0.603 | 10 | 56 |
| 370 | 10-j137 | 0.732-j0.612 | 12 | 47 |
| 375 | 10-j135 | 0.725-j0.619 | 12 | 47 |
| 380 | 10-j133 | 0.718-j0.625 | 10 | 47 |
| 385 | 10-j131 | 0.711-j0.631 | 10 | 47 |
| 390 | 10-j130 | 0.707-j0.634 | 10 | 43 |
| 395 | 10-j128 | 0.700-j0.641 | 10 | 43 |
| 400 | 10-j126 | 0.692-j0.647 | 10 | 43 |
| 405 | 10-j124 | 0.684-j0.653 | 10 | 39 |
| 410 | 10-j122 | 0.675-j0.660 | 10 | 39 |



| 415 | 10-j120 | 0.667-j0.667 | 10 | 39 |
|-----|---------|--------------|-----|----|
| 420 | 10-j118 | 0.658-j0.673 | 10 | 36 |
| 425 | 10-j117 | 0.653-j0.677 | 10 | 36 |
| 430 | 10-j115 | 0.643-j0.684 | 10 | 33 |
| 435 | 10-j114 | 0.638-j0.687 | 10 | 33 |
| 440 | 8-j112 | 0.635-j0.704 | 8.2 | 33 |

Table 4. Input Impedance Versus Frequency







13.2. Shutdown Function

Duty-cycled operation of the RF83L (often referred to as polling) is achieved by turning the RF83L on and off via the SHUT pin. The shutdown function is controlled by a logic state applied to the SHUT pin. When VSHUT is high, the device goes into low-power standby mode. This pin is pulled high internally; it must be externally pulled low to enable the receiver.

13.3. Power Supply Bypass Capacitors

VDDBB and VDDRF should be connected together directly at the IC pins. Supply bypass capacitors are strongly recommended. They should be connected to VDDBB and VDDRF and should have the shortest possible lead lengths. For best performance, connect VSSRF to VSSBB at the power supply only (that is, keep V_{SSBB} currents from flowing through the V_{SSRF} return path).

13.4. Increasing Selectivity with an Optional BandPass Filter

For applications located in high ambient noise environments, a fixed value band-pass network may be connected between the ANT pin and VSSRF to provide additional receive selectivity and input overload protection. A minimum input configuration is included in figure 2a. it provides some filtering and necessary overload protection.

13.5. Data Squelching

During quiet periods (no signal) the data output (DO pin) transitions randomly with noise. Most decoders can discriminate between this random noise and actual data but for some system it does present a problem. There are three possible approaches to reducing this output noise:

- 1) Analog squelch to raise the demodulator threshold
- 2) Digital squelch to disable the output when data is not present
- 3) Output filter to filter the (high frequency) noise glitches on the data output pin.

The simplest solution is add analog squelch by introducing a small offset, or squelch voltage, on the CTH pin so that noise does not trigger the internal comparator. Usually 20mV to 30mV is sufficient, and may be achieved by connecting a several-megohm resistor from the CTH pin to either V_{SS} or V_{DD} , depending on the desired offset polarity. Since the RF83L has receiver AGC noise at the internal comparator input is always the same, set by the AGC. The squelch offset requirement does not change as the local noise strength changes from installation to installation. Introducing squelch will reduce sensitivity and also reduce range. Only introduce an amount of offset sufficient to quiet the output. Typical squelch resistor values range from $6.8M\Omega$ to $10M\Omega$.

13.6. Wake-Up Function

The WAKEB output signal can be used to reduce system power consumption by enabling the rest of a system when an RF signal is present. The WAKEB is an output logic signal which goes active low when the IC detects a constant RF carrier. The wake-up function is unavailable when the IC is in shutdown mode.



To activate the Wake-Up function, a received constant RF carrier must be present for 128 counts or the internal system clock. The internal system clock is derived from the reference oscillator and is 1/256 the reference oscillator frequency. For example:

$$\begin{split} f_T &= 6.4 MHz \\ f_S &= f_T/256 = 25 kHz \\ P_S &= 1/f_S = 0.04 ms \\ 128 \ counts \ x \ 0.04 ms = 5.12 ms \end{split}$$

Where:

 f_T = reference oscillator frequency

 f_S = system clock frequency

 P_S = system clock period

The Wake-Up counter will reset immediately after a detected RF carrier drops. The duration of the Wake-Up signal output is then determined by the required wake up time plus an additional RF carrier on time interval to create a wake up pulse output.

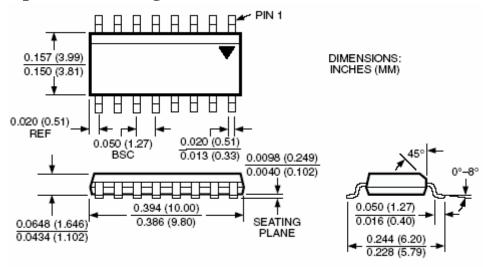
WAKEB Output Pulse Time = T_{WAKE} + Additional RF Carrier on Time

For designers who wish to use the wakeup function while squelching the output, a positive squelching offset voltage must be used. This simply requires that the squelch resistor be connected to a voltage more positive than the quiescent voltage on the CTH pin so that the data output is low in absence of a transmission.



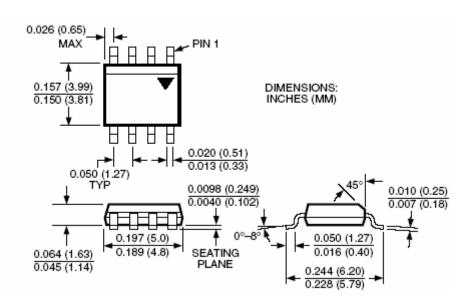
14. Package Information

14.1 16-pin SOP Package



16-Pin SOP (M)

14.2 8-pin SOP Package



8-Pin SOP (M)



14.3 16-pin SOP Top Marking

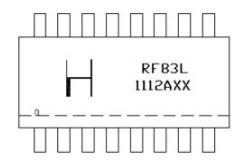


Figure 15.3 RF83L SOP Top Marking Table 15.3 Top Marking Explanation

| Line | Characters | Description |
|--------|------------------|---|
| Line 1 | | HopeRF's Logo. |
| | Part Number Code | There is format RF83L. |
| Line 2 | 11=Year | Assigned by the assembly House. Corresponds to |
| | 12=Work Week | the year and work weak of the assembly date. |
| | A=Version Number | Version Number, such as "A". |
| | XX=Trace Code | Manufacturing code characters from the Markings |
| | | Section of the Assembly Order form. |

14.4 8-pin SOP Top Marking

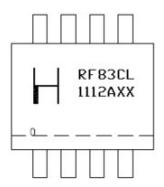


Figure 15.4 RF83(A/B/C/D)L SOP Top Marking
Table 15.4 Top Marking Explanation

| Line | Characters | Description | |
|--------|------------------|---|--|
| Line 1 | | HopeRF's Logo. | |
| | Part Number Code | There are four formats RF83AL, RF83BL, RF83CL, or RF83DL. | |
| | 11=Year | Assigned by the assembly House. Corresponds to | |
| | 12=Work Week | the year and work weak of the assembly date. | |
| Line 2 | A=Version Number | Version Number, such as "A". | |
| | XX=Trace Code | Manufacturing code characters from the Markings | |
| | | Section of the Assembly Order form. | |



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